

RM8205F

Descriptions

N-channel Double MOSFET in a SOT23-6 Plastic Package.

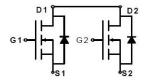
Features

advanced trench technology to provide excellent $R_{DS(on)}$, low gate charge and operation with gate voltages as low as 2.5V.

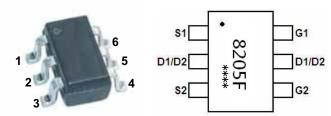
Applications

Use as a Battery protection , Switching application.

Equivalent Circuit



Pinning



Marking

| Marking | 8205F |
|---------|-------|
|---------|-------|

2018-06/33 REV:O

Absolute Maximum Ratings(Ta=25 °C)

| Parameter | Symbol | Rating | Unit | |
|--|--------------------------|-----------|------|--|
| Drain-Source Voltage | V _{DS} | 20 | V | |
| Drain Current - Continuous | I _D (Ta=25℃) | 6.0 | А | |
| Drain Current - Continuous | I _D (Ta=100℃) | 4.8 | А | |
| Drain Current – Pulsed | I _{DM} | 20 | А | |
| Gate-Source Voltage | V _{GS} | ±12 | V | |
| Maximum Power Dissipation | P _D (Ta=25℃) | 1.14 | W | |
| Thermal Resistance Junction-to-Ambient | R _{eJA} | 110 | °C/W | |
| Junction Temperature | T _j | 150 | °C | |
| Storage Temperature Range | T _{stg} | -55 ~ 150 | °C | |

Electrical Characteristics(Ta=25°C)

| Parameter | Symbol | Test Conditions | | Min | Тур | Max | Unit |
|--|---------------------|----------------------------------|------------------------|-----|------|------|------|
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V | I _D =250μA | 20 | | | V |
| Drain-Source Leakage Current(T _i =25℃) | I _{DSS} | V _{DS} =20V | V _{GS} =0V | | | 1 | μA |
| Drain-Source Leakage Current(T _i =70℃) | I _{DSS} | V _{DS} =16V | V _{GS} =0V | | | 25 | μΑ |
| Gate-Source Leakage Current | I_{GSS} | V _{GS} =±10V | $V_{DS}=0V$ | | | ±100 | nA |
| Gate Threshold Voltage | $V_{GS(th)}$ | V _{DS} =V _{GS} | I _D =250μA | 0.5 | | 1.2 | V |
| Static Drain-Source On-Resistance | R _{DS(on)} | V _{GS} =4.5V | I _D =1.0A | | 11.5 | 17 | mΩ |
| | | V _{GS} =2.5V | I _D =1.0A | | 16.5 | 22 | mΩ |
| | | V _{GS} =4.5V | I _D =6.0A | | 14 | 20 | mΩ |
| | | V _{GS} =2.5V | I _D =5.2A | | 17 | 24 | mΩ |
| Forward Transconductance | g FS | V _{DS} =5.0V | I _D =4.0A | 5 | | | S |
| Forward On Voltage | V _{SD} | V _{GS} =0V | I _S =1.7A | | | 1.2 | V |
| Input Capacitance | C _{iss} | | | | 1035 | | pF |
| Output Capacitance | C _{oss} | V _{DS} =20V f=1.0MHz | $V_{GS}=0V$ | | 320 | | pF |
| Reverse Transfer Capacitance | C _{rss} | | | | 150 | | pF |
| Turn-on Delay Time | t _{d(on)} | | | | 30 | | ns |
| Rise Time | t _r | | $I_D=1A$ $R_G=6\Omega$ | | 70 | | ns |
| Turn-off Delay Time | t _{d(off)} | | | | 40 | | ns |
| Fall Time | t _f | | | | 65 | | ns |

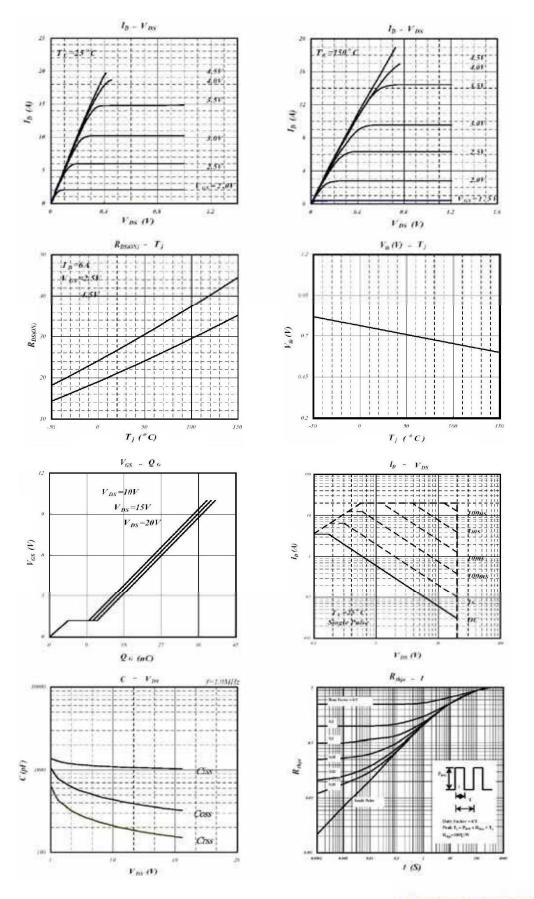
Notes



^{1,} Surface Mounted on FR4 Board, $t \le 10$ sec.

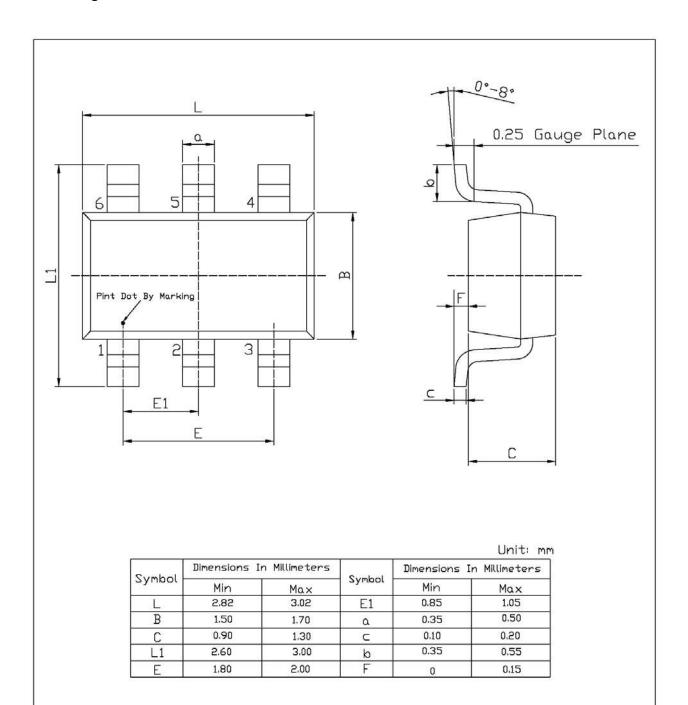
² Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤2%.

RATING AND CHARACTERISTICS CURVES (RM8205F)





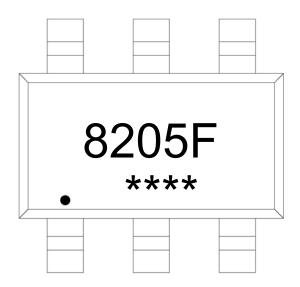
Package Dimensions



S0T23-6



Marking Instructions



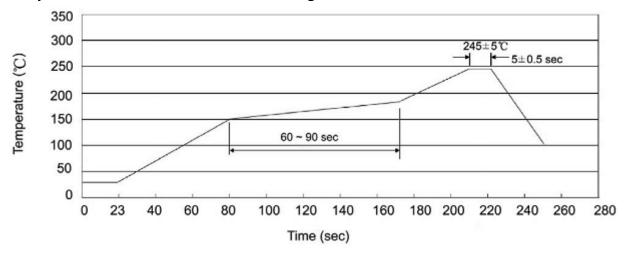
Note:

8205F: Product Type Code.

****: Date code change with manufacturing date.



Temperature Profile for IR Reflow Soldering(Pb-Free)



Notes:

1.Preheating:25~150 °C, Time:60~90sec.

2.Peak Temp.:245 ±5°C, Duration:5±0.5sec.

3. Cooling Speed: 2~10°C/sec.

Resistance to Soldering Heat Test Conditions

Temp:260±5°C Time:10±1 sec

Packaging SPEC.

REEL

| Ī | Package Type | | Units | | | | | nsion | (unit: mm³) | |
|---|--------------|------------|-----------------|-----------------|-----------------------|-----------------|-------|-------------|-------------|--|
| | | Units/Reel | Reels/Inner Box | Units/Inner Box | Inner Boxes/Outer Box | Units/Outer Box | Reel | Inner Box | Outer Box | |
| ĺ | SOT23-5/6 | 3,000 | 10 | 30,000 | 4 | 120,000 | 7″ ×8 | 210×205×205 | 445×230×435 | |



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